

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Solanki, et al. §
Serial No.: Unknown §
Filed: Herewith §
Title: A Method Of Depositing A §
Metallic Film On A Substrate §
Docket: D8848-02

Commissioner for Patents
Washington, D.C. 20231

POWER OF ATTORNEY BY ASSIGNEE

As assignee of record of the entire interest of the above-identified application, I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the U.S. Patent and Trademark Office connected therewith.


Richard T. Redano Reg. No. 32,292
Gary R. Maze Reg. No. 42,851

Please direct all correspondence to: **Richard T. Redano, Duane Morris LLP, One Greenway Plaza, Suite 500, Houston, Texas, 77046.** Direct telephone calls to: **Richard T. Redano at (713) 552-9706.**

Oregon Health & Science University

2-1-02
Date

By:


Name: Todd T. Sherer, Ph.D.
Title: Director of Technology &
Research Collaborations
Oregon Health & Science
University
3181 SW Sam Jackson Park Road
Portland, OR 97201-3098

DECLARATION

As the below named inventors, we hereby declare that:

Our residences, post office addresses, and citizenships are as stated below.

We believe we are the original, first, and joint inventors of the subject matter which is claimed and for which a patent is sought on the invention entitled: **A Method Of Depositing A Metallic Film On A Substrate**, the specification of which is attached hereto.

We hereby state that we have reviewed and understand the contents of the above identified specification, including the claims.

We acknowledge the duty to disclose information which is material to patentability as defined in 37 C.F.R. § 1.56.

We hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

PRIOR FOREIGN APPLICATION(S)

NONE

We hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, we acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a), regarding events which occurred between the filing date of the prior application and the national or PCT International filing date of this application:

(Application Serial No.)	(Filing Date)	(Status)
09/968,370	October 1, 2001	Pending

We hereby direct that all correspondence and telephone calls be addressed to Richard T. Redano, Duane Morris LLP, One Greenway Plaza, Suite 500, Houston, Texas 77046, (713) 552-9900.

We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

FULL NAME AND ADDRESS OF FIRST INVENTOR:

Name: Rajendra Solanki
Residence: 20800 NW Wallula Court
Portland, OR 97229
Post Office Address: same
Citizenship: United States

Date

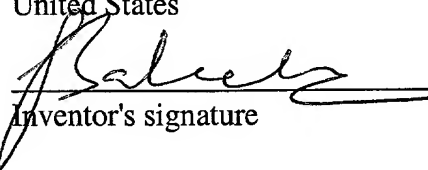
Inventor's signature

FULL NAME AND ADDRESS OF SECOND INVENTOR:

Name: Balu Pathangey
Residence: 6842 S. 24th Place
Phoenix, AZ 85042
Post Office Address: same
Citizenship: United States

02/12/02

Date



Inventor's signature

DECLARATION

As the below named inventors, we hereby declare that:

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FULL NAME AND ADDRESS OF FIRST INVENTOR:

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Citizenship: United States

Feb 18, 2002
Date

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Citizenship: United States

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